

# Chip Scale Review

## 2017 Editorial Calendar

**(Editorial close date: 11/20)**

**January • February**

\* indicates show distribution

Industry forecast	<ul style="list-style-type: none"> <li>• <b>SEMI European 3D Summit</b> Grenoble, France (Jan 23-25)</li> <li>• <b>SMTA Pan Pac Microelectronics Symposium *</b> Kauai, Hawaii (Feb 6-9)</li> <li>• <b>SEMICON Korea</b> Seoul, Korea (Feb 8-10)</li> <li>• <b>APEX Expo</b> San Diego, CA (Feb 14-16)</li> <li>• <b>BiTS Workshop*</b> Mesa, AZ (March 5-8)</li> <li>• <b>IMAPS DPC*</b> Fountain Hills, AZ (March 6-9)</li> <li>• <b>SEMICON China*</b> Shanghai, China (March 14-16)*</li> </ul>
Semiconductor merger & consolidation	
Future of packaging with silicon photonics	
Comparison & highlights on the latest FOWLP technology trends	
Cu pillars for 3D stacking	
Plasma dicing	
Electronic assembly reliability	
Testing of MEMS / sensors in HVM	
Testing IoT devices	
High frequency test sockets	

**Ad Space Close Jan 6 - Ad Materials Close Jan 11**

**(Editorial close date: 1/6)**

**March • April**

\* indicates show distribution

Metrology for advanced packaging applications	<ul style="list-style-type: none"> <li>• <b>SEMICON SE Asia</b> Penang, Malaysia (Apr 25-27)</li> <li>• <b>ECTC *</b> Lake Buena Vista, FL (May 30- June 2)</li> </ul>
3D integration technology for high-density, high performance ICs	
Die attach solutions	
Electronic materials	
Embedded and fan-out packaging	
Hi density FO package for RF applications	
Advances in FOWLP	
Additive manufacturing for packaging applications	
International directory of IC packaging foundries	

**Ad Space Close Feb 10 - Materials Close Feb 15**

**(Editorial close date: 3/10)**

**May • June**

\* indicates show distribution

Thin wafer handling	<ul style="list-style-type: none"> <li>• <b>IEEE/SW Test Workshop (SWTW)</b> San Diego, CA (June 5-8)</li> <li>• <b>Sensors Expo</b> San Jose, CA (June 27-29)</li> <li>• <b>SEMICON West *</b> San Francisco, CA (July 12-14)</li> </ul>
Wafer-level test	
Advances in thermal management	
Adhesives, underfill, encapsulants	
System in package (SiP)	
Semiconductor mergers & acquisitions	
Lithography solutions for MEMS	
Automotive application solutions	
Feature: 50 years of CEA-Leti – past, present, future	

**Ad Space Close May 19 - Ad Materials Close May 24**